MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

WQFN16 3x3, 0.5P
CASE 510CF
ISSUE O

DATE 31 Aug 2016

NOTES:
A. SIMILAR TO JEDEC REGISTRATION MO−217.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER
D. LAND PATTERN RECOMMENDATION IS
   EXISTING INDUSTRY LAND PATTERN.

DETAIL A
SCALE : 2X

DOCUMENT NUMBER: 98AON13647G
STATUS: ON SEMICONDUCTOR STANDARD
NEW STANDARD: ON SEMICONDUCTOR STANDARD
DESCRIPTION: WQFN16 3X3, 0.5P
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